



*GoLED*

**XSA-325 Pin Fin LED Heat Sink  $\Phi$ 78mm for Xicato**

**Features VS Benefits**

- \* The XSA-325 Xicato Pin Fin LED Heat Sinks are specifically designed for luminaires using the Xicato LED engines.
- \* Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- \* For spotlight and downlight designs from 1,000 to 2,700 lumen.
- \* Thermal resistance range  $R_{th}$  3.03°C/W.
- \* Xicato Thermal Class J , ( 60° tilt angle, 40°C ambient ) .
- \* Modular design with mounting holes foreseen for direct mounting of Xicato XSA/ XIM/ XTM modules.
- \* Diameter 78.0mm - standard height 30.0mm, Other heights on request.
- \* Forged from highly conductive aluminum.



- \*The XSA-325 Xicato Pin Fin Heat Sink is standard foreseen from a variety of mounting holes which allow direct mounting of all Xicato Spot and down light LED modules and secondary optics on the Pin Fin LED heat sink.
- \*In this way mechanical afterwork and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED coolers.
- \*Below you find an overview of Xicato LED modules which standard fit on the XSA-325 Pin Fin LED Heat Sinks.
- \*MingFa performs thermal validation tests on each of the LED modules mounted on the LED cooler and publishes.
- \*This data in the Xicato Cooler thermal validation reports.
- \*For a full overview of available LED coolers for Xicato LEDs, please refer to the Xicato LED cooler overview on.



**Xicato LED Modules directly Mounting Options**

**Xicato XSM LED modules name :**

XSM8027-xxxx ;	XSM9530-xxxx ;
XSM8030-xxxx ;	XSM9540-xxxx ;
XSM8040-xxxx ;	XSMV830-xxxx ;
XSM9527-xxxx ;	

Direct mounting with 3 screws M3 x 12mm;  
Green indicator marks.

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**Xicato XIM LED modules name :**

XIM198027-xxx ;	XIM198040-xxx ;	XIM09-V9xxxxxx ;
XIM198030-xxx ;	XIM19V830-xxx ;	
XIM198035-xxx ;	XIM0980 xxxxxx ;	

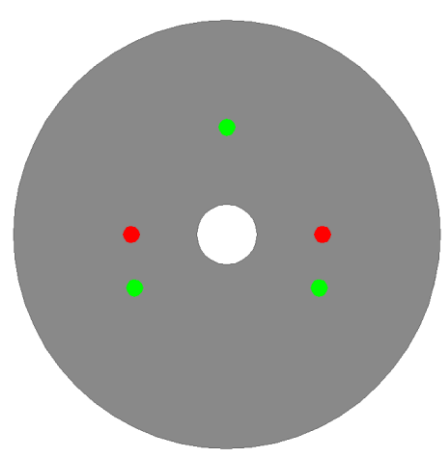
Direct mounting with 3 screws M3 x 20mm;  
Green indicator marks.

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**Xicato XTM LED modules:**

XTM19-8027-xxx ;	XTM19-8040-xxx ;	XTM0995 xxxxxx ;
XTM19-8030-xxx ;	XTM19-V830-xxx ;	
XTM19-8035-xxx ;	XTM09-V9xxxxxx ;	

Direct mounting with 3 screws M3 x 10mm;  
Green indicator marks.  
Direct mounting by Zhaga mounting holes with 2 screws M3 x 8mm;  
Red indicator marks.



#### Mounting Options and Drawings & Dimensions

Example: XSA-325-M3-B-1

Example: XSA-325-M3-**1**-**2**

**1** Anodising Color

B-Black

C-Clear

Z-Custom

**2** Mounting Options - see graphics for details Combinations available

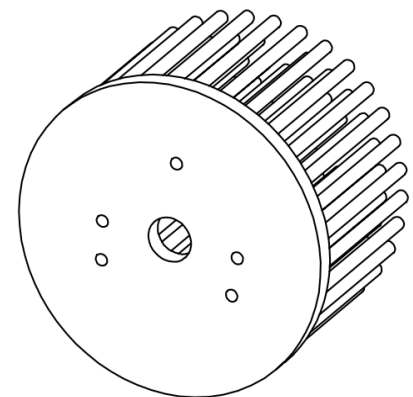
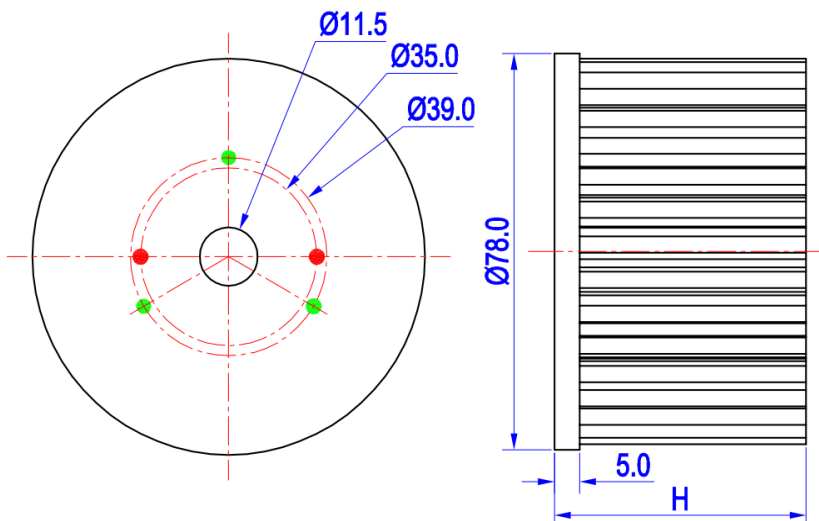
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means option 1 and 2 combined

**Notes:**

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	PART NUMBER	THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
N	XSA-325-M3-#-N	M3	6.5mm	39.0mm/ 3-@120°
1	XSA-325-M3-#-1	M3	6.5mm	35.0mm/ 2-@180° (Zhaga Book 3)
2	XSA-325-M3-#-2	M3	$\Phi 11.5\text{mm}$	Through-Hole



**The product data table**

	<b>Model No.</b>	XSA-325
	<b>Heatsink Size</b>	Φ78xH30mm
	<b>Heatsink Material</b>	AL1070
	<b>Finish</b>	Black Anodized
	<b>Weight (g)</b>	138.0
	<b>Dissipated power (T<sub>hs-amb</sub>,50°C)</b>	16.5 (W)
	<b>Cooling surface area (mm<sup>2</sup>)</b>	46643
	<b>Thermal Resistance (R<sub>hs-amb</sub>)</b>	3.03 (°C/W)

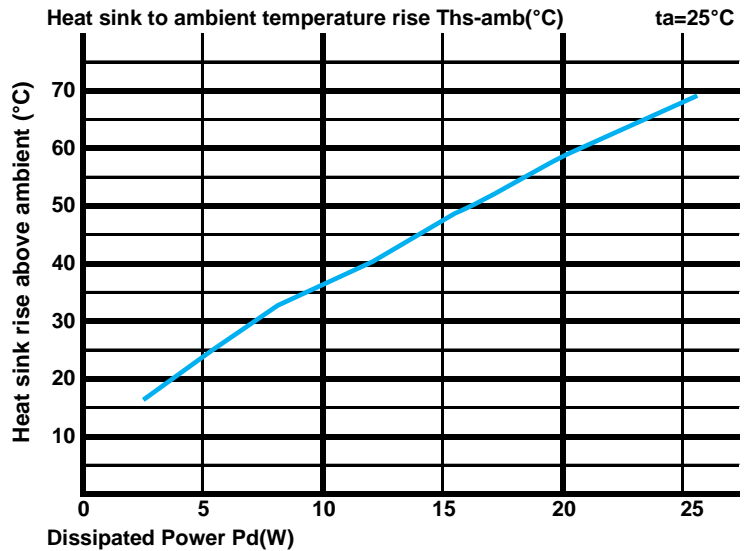
**The thermal data table**

\* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

\*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light efficiency of the LED module;

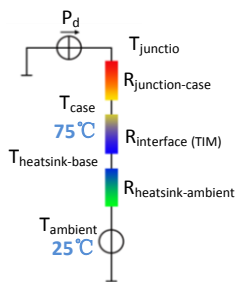
Dissipated Power Pd(W)	Pd = Pe x (1-ηL)	Heat sink to ambient thermal resistance R <sub>hs-amb</sub> (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		XSA-325	
5.0		4.80	24.0
10.0		3.60	36.0
15.0		3.13	47.0
20.0		2.95	59.0
25.0		2.72	68.0



\*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



\*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula:  $\theta = (T_{hs} - T_a) / P_d$

$\theta$  - Thermal Resistance [°C/W]; T<sub>hs</sub> - Heatsink temperature; T<sub>a</sub> - Ambient temperature;

\*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is R<sub>junction-case</sub>, the thermal resistance of the TIM outside the package is R<sub>interface (TIM)</sub> [°C/W], the thermal resistance with the heat sink is R<sub>heatsink-ambient</sub> [°C/W], and the ambient temperature is T<sub>ambient</sub> [°C].

\*Thermal resistances outside the package R<sub>interface (TIM)</sub> and R<sub>heatsink-ambient</sub> can be integrated into the thermal resistance R<sub>case-ambient</sub> at this point. Thus, the following formula is also used:

$$T_{\text{junction}} = (R_{\text{junction-case}} + R_{\text{case-ambient}}) \cdot P_d + T_{\text{ambient}}$$